

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,094,291 B2
APPLICATION NO. : 09/893316
DATED : August 22, 2006
INVENTOR(S) : Reardon et al.

Page 1 of 3

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page item (56), Include the cited references as listed below:

US-2,774,364 12-18-1956 Brobeil	US-4,668,334 05-26-1987 Doornveld
US-3,107,034 10-15-1963 Dunnous	US-4,687,542 08-18-1987 Davis et al.
US-4,688,918 08-25-1987 Suzuki et al.	US-4,693,777 09-15-1987 Hazano et al.
US-4,709,858 12-01-1987 Stern et al.	US-4,724,317 02-09-1988 Brown et al.
US-4,736,758 04-12-1988 Kusuhara	US-4,745,422 05-17-1988 Matsuoka et al.
US-4,749,440 06-07-1988 Blackwood et al.	US-4,778,559 10-18-1988 McNeilly
US-4,788,994 12-06-1988 Shinbara	US-4,793,282 12-27-1988 Greenberg et al.
US-4,797,316 01-10-1989 Hecq et al.	US-4,804,560 02-14-1989 Shioya et al.
US-4,830,882 05-16-1989 Ichinose et al.	US-4,832,580 05-23-1989 Tsuyoshi et al.
US-4,857,142 08-15-1989 Syverson	US-4,863,066 09-05-1989 Uffenheimer et al.
US-4,865,641 09-12-1989 Sasse et al.	US-4,871,417 10-03-1989 Nishizawa et al.
US-4,875,824 10-24-1989 Moe et al.	US-4,885,047 12-05-1989 Ury et al.
US-4,895,099 01-23-1990 D'Amato	US-4,900,395 02-13-1990 Syverson et al.
US-4,923,054 05-08-1990 Ohtani et al.	US-4,924,800 05-15-1990 Tanaka
US-4,932,353 06-12-1990 Kawata et al.	US-4,936,940 06-26-1990 Kawasumi et al.
US-4,938,691 07-03-1990 Ohkase et al.	US-4,944,837 07-31-1990 Nishikawa
US-4,960,406 10-02-1990 Gorodissky et al.	US-4,977,688 12-18-1990 Roberson, Jr. et al.
US-4,987,854 01-29-1991 Hall	US-4,996,080 02-26-1991 Daraktchiev
US-5,002,008 03-26-1991 Ushijima et al.	US-5,056,462 10-15-1991 Perkins et al.
US-5,065,692 11-19-1991 Hollesen et al.	US-5,085,560 02-04-1992 Thompson et al.
US-5,094,884 03-10-1992 Hillman et al.	US-5,127,362 07-07-1992 Iwatsu et al.
US-5,168,886 12-08-1992 Thompson et al.	US-5,168,887 12-08-1992 Thompson et al.
US-5,183,508 02-02-1993 Cholinski	US-5,224,503 07-06-1993 Thompson et al.
US-5,232,328 08-03-1993 Owczarz et al.	US-5,235,995 08-17-1993 Bergman et al.
US-5,252,137 10-12-1993 Tateyama et al.	US-5,270,248 12-14-1993 Rosenblum et al.
US-5,358,740 10-25-1994 Bornside et al.	US-5,378,511 01-03-1995 Cardinali et al.
US-5,395,803 03-07-1995 Adams	US-5,403,617 04-04-1995 Haaland
US-5,429,912 07-04-1995 Neoh	US-5,431,421 07-11-1995 Thompson et al.
US-3,148,085 09-08-1964 Wiegmann	US-3,313,266 04-11-1967 Kelson
US-3,326,717 06-20-1967 Gregor et al.	US-3,339,297 09-05-1967 Stinn et al.
US-3,489,608 01-13-1970 Jacobs et al.	US-3,585,668 06-22-1971 Jaccodine et al.
US-3,601,627 08-24-1971 Booher	US-3,727,620 04-17-1973 Orr
US-3,773,578 11-20-1973 Glendinning et al.	US-4,056,462 11-01-1977 Li et al.
US-4,065,692 12-27-1977 Osterhout	US-4,085,560 04-25-1978 McClosky
US-4,094,884 06-13-1978 Kelly	US-4,127,362 11-28-1978 Fladby

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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

US-4,139,333 02-13-1979 Sipos	US-4,159,917 07-03-1979 Gluck
US-4,161,356 07-17-1979 Giffin et al.	US-4,168,886 09-25-1979 Grifaliunas
US-4,168,887 09-25-1979 Yevick	US-4,183,508 01-15-1980 Michelet et al.
US-4,192,087 03-11-1980 Salomon	US-4,222,345 09-16-1980 Bergfelt et al.
US-4,224,503 09-23-1980 Gijzel et al.	US-4,232,328 11-04-1980 Hartman et al.
US-4,246,088 01-20-1981 Murphy et al.	US-4,252,137 02-24-1981 Cohen
US-4,264,374 04-28-1981 Beyer et al.	US-4,267,212 05-12-1981 Sakawaki
US-4,270,248 06-02-1981 Akashi	US-4,282,825 08-11-1981 Nagatomo et al.
US-4,290,384 09-22-1981 Ausschnitt et al.	US-4,313,266 02-02-1982 Tam
US-4,339,297 07-13-1982 Aigo	US-4,344,743 08-17-1982 Bessman et al.
US-4,378,511 03-29-1983 Simovits, Jr.	US-4,403,617 09-13-1983 Tretinyak
US-4,416,213 11-22-1983 Sakiya	US-4,429,912 02-07-1984 Smith, Jr.
US-4,429,983 02-07-1984 Cortellino et al.	US-4,437,812 03-20-1984 Abu-Shumays et al.
US-4,457,259 07-03-1984 Samuels	US-4,457,419 07-03-1984 Ogami et al.
US-4,475,665 10-09-1984 Norton	US-4,483,665 11-20-1984 Hauser
US-4,519,846 05-28-1985 Aigo	US-4,542,038 09-17-1985 Odaka et al.
US-4,580,699 04-08-1986 Black et al.	US-4,588,185 05-13-1986 Shoda et al.
US-4,590,094 05-20-1986 Ringer, Jr.	US-4,601,627 07-22-1986 Oka et al.
US-4,605,479 08-12-1986 Faith, Jr.	US-4,651,440 03-24-1987 Karl
JP-45-40458 12/1970	JP-1-204427 08-17-1989 Hitachi Ltd.
JP-1-304732 11-17-1998 Kubota Corp.	JP-231330 11-16-1985 Seiichirou Sougou
JP-54-161275 12-20-1979 Toshiba Corp.	JP-56-88320 07-17-1981 Fujitsu Ltd.
JP-58-19475 02-04-1983 Asahi Chem Ind Co. Ltd	JP-59-166675 09-20-1984 Fujitsu KK
JP-61-148820 07-07-1986 Hitachi Ltd.	
JP-54-71991 06-08-1979 Matsushita Electronics Corp.	
JP-3010-974 08-15-1979 Matsushita Elec Ind. Co. Ltd.	

A Mechanism of Particle Generation and a Method to Suppress Particles in Vapor HF/H₂O System", in Shigeo Onishi, et al., Extended abstracts of the 22nd (1990 International) Conference on Solid State Devices and Materials, Sendai, 1990, pp. 1127-1139.

BEYER et al., "IBM Tech. Disc. Bull," Etching of SiO₂ in Gaseous HF/H₂O, Vol 19, No. 7, December 1976, p 2513.

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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

BRISKA, M. et al. "Process for Reducing Gold or Copper Wafer Contamination During Oxide Removal," IBM Technical Disclosure Bulletin, Vol 19, No. 7, p. 2574, December 1976.

BURGGRAAF, Pieter, "Vapor-Phase Cleaning at Reduced Pressure," Semiconductor International, p 36 (Dec. 1989).

IBM Technical Disclosure Bulletin, Vol. 32, No. 1, June 1989, "Upside-Down Resist Coating of Semiconductor Wafers".

MOREAU et al., "Wafer Cleaner System," IBM Technical Disclosure Bulletin, Vol 19, No. 10, pp 2905-2906 (March 1972).

Product Brochure, "Preliminary Product Information-EDGE 2000", Advantage, Production Technology Incorp (1989).

VAN DER HEIDE, P.A.M., et al., "Etching of Thin SiO₂ Layers Using Wet HR Gas," J. Vac. Sci. Technol. A7(3), pp. 1719-1723, (May/June 1989).

Signed and Sealed this

Twenty-third Day of June, 2009



JOHN DOLL

Acting Director of the United States Patent and Trademark Office